SLVS019F - OCTOBER 1987 - REVISED JULY 1999

- Power-On Reset Generator
- Automatic Reset Generation After Voltage Drop
- RESET Defined When V<sub>CC</sub> Exceeds 1 V
- Wide Supply-Voltage Range . . . 3.5 V to 18 V
- Precision Overvoltage and Undervoltage Sensing
- 250-mA Peak Output Current for Driving SCR Gates
- 2-mA Active-Low SCR Gate Drive for False-Trigger Protection
- Temperature-Compensated Voltage Reference
- True and Complementary Reset Outputs
- Externally Adjustable Output Pulse Duration

#### **DW OR N PACKAGE** (TOP VIEW) 1RESIN Γ 16 VCC 15 2RESIN 1CT □ 1RESET **∏** 3 14 7 2CT 13 1 2RESET 1RESET 1 4 12 2 RESET 1VSU **1** 5 11 | 2VSU 1VSO 10 2VSO 1SCR DRIVE 7 9 7 2SCR DRIVE GND [

## description

The TL7770 is an integrated-circuit system supervisor designed for use as a reset controller in microcomputer and microprocessor power-supply systems. This device contains two independent supply-voltage supervisors that monitor the supplies for overvoltage and undervoltage conditions at the VSO and VSU terminals, respectively. When  $V_{CC}$  attains the minimum voltage of 1 V during power up, the  $\overline{RESET}$  output becomes active (low). As  $V_{CC}$  approaches 3.5 V, the time-delay function activates, latching RESET and  $\overline{RESET}$  active (high and low, respectively) for a time delay (t<sub>d</sub>) after system voltages have achieved normal levels. Above  $V_{CC} = 3.5$  V, taking  $\overline{RESIN}$  low activates the time-delay function during normal system-voltage levels. To ensure that the microcomputer system has reset, the outputs remain active until the voltage at VSU exceeds the threshold value,  $V_{IT+}$ , for a time delay, which is determined by an external timing capacitor such that:

$$t_d \approx 20 \times 10^3 \times capacitance$$

where t<sub>d</sub> is in seconds and capacitance is in farads.

The overvoltage-detection circuit is programmable for a wide range of designs. During an overvoltage condition, an internal silicon-controlled rectifier (SCR) is triggered, providing 250-mA peak instantaneous current and 25-mA continuous current to the SCR gate drive terminal, which can drive an external high-current SCR gate or an overvoltage-warning circuit.

The TL7770C series is characterized for operation from 0°C to 70°C. The TL7770I series is characterized for operation from –40°C to 85°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

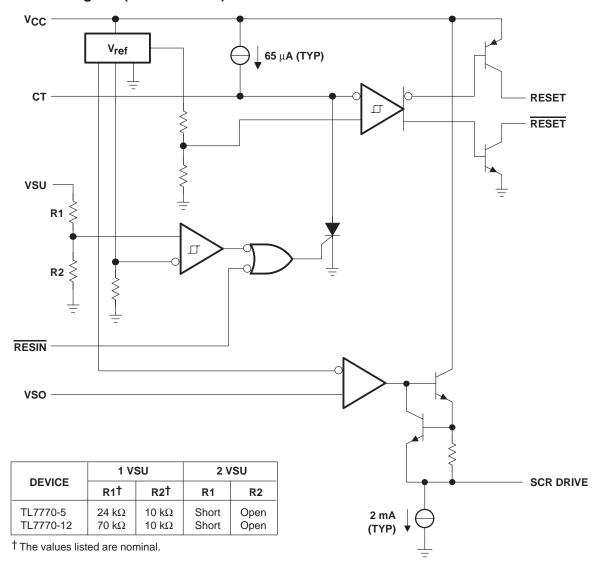


#### **AVAILABLE OPTIONS**

	PACKAGED	DEVICES	CHIP FORM		
TA	SMALL OUTLINE (DW)	PLASTIC DIP (N)	(Y)		
0°C to 70°C	TL7770-5CDW TL7770-12CDW	TL7770-5CN TL7770-12CN	TL7770-5Y TL7770-12Y		
–40°C to 85°C	TL7770-5IDW	TL7770-5IN	_		

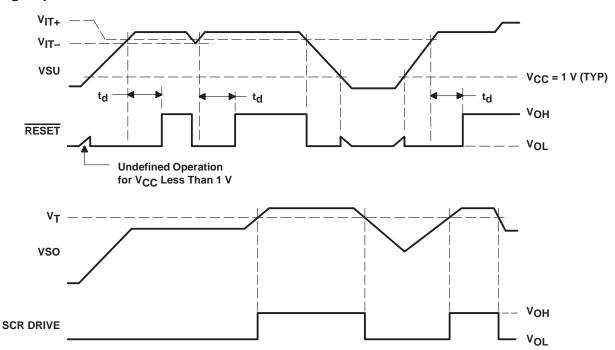
DW package is available taped and reeled. Add the suffix R to the device type (e.g., TL7770-5CDWR). Chip forms are tested at 25°C.

## functional block diagram (each channel)





## timing requirements



## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V <sub>CC</sub> (see Note 1)	20 V
Input voltage range, V <sub>I</sub> : 1VSU, 2VSU, 1VSO, and 2VSO (see Note 1)	
Low-level output current (1RESET and 2RESET), IOL	20 mA
High-level output current (1RESET and 2RESET), IOH	–20 mA
Package thermal impedance, θ <sub>JA</sub> (see Notes 2 and 3): DW package	57°C/W
N package	88°C/W
Lead temperature 1,6 mm (1/16 in) from case for 10 seconds: DW or N package	260°C
Storage temperature range, T <sub>sta</sub>	-65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values are with respect to the network ground terminal.
  - 2. Maximum power dissipation is a function of  $T_J(max)$ ,  $\theta_{JA}$ , and  $T_A$ . The maximum allowable power dissipation at any allowable ambient temperature is  $P_D = (T_J(max) T_A)/\theta_{JA}$ . Operating at the absolute maximum  $T_J$  of 150°C can impact reliability.
  - 3. The package thermal impedance is calculated in accordance with JESD 51, except for through-hole packages, which use a trace length of zero.



# TL7770-5, TL7770-12 DUAL POWER-SUPPLY SUPERVISORS

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## recommended operating conditions

		MIN	MAX	UNIT
Supply voltage, V <sub>CC</sub>		3.5	18	V
Input voltage range, V <sub>I</sub> (see Note 4)	1VSU, 2VSU, 2VSO, 1VSO	0	18	V
Output voltage, VO (1CT, 2CT)			5	V
High-level input voltage range, VIH (1RESIN, 2RESIN)		2	18	V
Low-level input voltage range, V <sub>IL</sub> (1RESIN, 2RESIN)	0	0.8	V	
Output sink current, IO (1CT, 2CT)		50	μΑ	
High-level output current, IOH (1RESET, 2RESET)			-16	mA
Low-level output current, IOL (1RESET, 2RESET)			16	mA
Continuous output current, IO (1SCR DRIVE, 2SCR DRIVE)			25	mA
Timing capacitor, C <sub>T</sub>			10	μF
Operating free air temperature Ta	TL7770C series		70	°C
Operating free-air temperature, T <sub>A</sub>	TL7770I series	-40	85	°C

NOTE 4: The algebraic convention, in which the least positive (most negative) value is designated minimum, is used in this data sheet for logic voltage levels only.



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# electrical characteristics over recommended operating conditions (unless otherwise noted) supply supervisor section

	PARAME	TER	TEST CONDITIONS†	TL7 TL7 TL	UNIT			
				MIN	TYP‡	MAX		
V0	High-level output voltage	RESET	I <sub>OH</sub> = -15 mA	V <sub>CC</sub> -1.5			V	
VOH	r light-level output voltage	SCR DRIVE	$I_{OH} = -20 \text{ mA}$	V <sub>CC</sub> -1.5			V	
VOL	Low-level output voltage	RESET	I <sub>OL</sub> = 15 mA			0.4	V	
		TL7770-5 (5-V sense, 1VSU)		4.46		4.64		
VIT	VIT- Undervoltage input threshold at VSU (negative-going)	TL7770-12 (12-V sense, 1VSU)	$T_A = MIN \text{ to MAX}$	10.68		11.12	٧	
VII-		TL7770-5, TL7770-12 (programmable sense, 2VSU)		1.47		1.53		
		TL7770-5 (5-V sense, 1VSU)		15			m∨	
\ \/.	Hysteresis at VSU	TL7770-12 (12-V sense, 1VSU)	$T_A = MIN \text{ to MAX}$	36				
Vhys	(V <sub>IT+</sub> – V <sub>IT</sub> _)	TL7770-5, TL7770-12 (programmable sense, 2VSU)	TA = WIIN to WAX		5		IIIV	
VT	Overvoltage threshold at VSO	TL7770-5, TL7770-12 (VSO)	$T_A = MIN \text{ to } MAX$	2.48		2.68	V	
1.	Input current	RESIN	V <sub>I</sub> = 5.5 V or 0.4 V			-10		
1	input current	VSO	V <sub>I</sub> = 2.4 V		0.5	2	μΑ	
ІОН	High-level output current	RESET	V <sub>O</sub> = 18 V			50	μΑ	
loL	Low-level output current	RESET	V <sub>O</sub> = 0			-50	μΑ	
ЮН	Peak output current	SCR DRIVE	Duration = 1 ms	250			mA	

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified in the recommended operating conditions.

#### total device

	PARAMETER	TEST CONDITION	TEST CONDITIONS†					
			MIN	TYP‡	MAX			
V <sub>res</sub> §	Power-up reset voltage	V <sub>CC</sub> = VSU			0.8	1	V	
loo	Supply current	1 <u>VSU =</u> 18 V, 2 <u>VSU =</u> 2 V, 1RESIN and 2RESIN at V <sub>CC</sub> ,	T <sub>A</sub> = 25°C			5	mΛ	
Icc	Зирріу сипені	1VSO and 2VSO at 0 V	$T_A = MIN \text{ to } MAX$			6.5	mA	

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified in the recommended operating conditions. ‡ Typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_{\underline{A}} = 25^{\circ}\text{C}$ . § This is the lowest voltage at which RESET becomes active.



 $<sup>\</sup>ddagger$  Typical values are at VCC = 5 V, TA = 25°C.

## TL7770-5, TL7770-12 **DUAL POWER-SUPPLY SUPERVISORS**

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# electrical characteristics over recommended operating conditions (unless otherwise noted) supply supervisor section

	PARAMETER		TEST CONDITIONS	T TL	UNIT			
			CONDITIONS	MIN	TYP†	MAX	1 1	
		TL7770-5 (5-V sense, 1VSU)		4.46		4.64		
V <sub>IT</sub> _	Undervoltage input threshold at VSU	TL7770-12 (12-V sense, 1VSU)	$T_A = MIN \text{ to MAX}$	10.68		11.12	] ,	
(negative-going)	TL7770-5, TL7770-12 (programmable sense, 2VSU)	TA = WIIIV to WIAX	1.47		1.53	v		
		TL7770-5 (5-V sense, 1VSU) 15						
V <sub>hys</sub>	Hysteresis at VSU	TL7770-12 (12-V sense, 1VSU)	$T_A = MIN \text{ to MAX}$	36			m <sub>V</sub>	
vilys	$(V_{ T+} - V_{ T-})$	TL7770-5, TL7770-12 (programmable sense, 2VSU)	I A = WIII to Will UK		5		1117	
VT	Overvoltage threshold at VSO	TL7770-5, TL7770-12 (VSO)	$T_A = MIN \text{ to MAX}$	2.48		2.68	V	
Ц	Input current	VSO	V <sub>I</sub> = 2.4 V		0.5		μΑ	

<sup>†</sup> Typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C.

#### total device

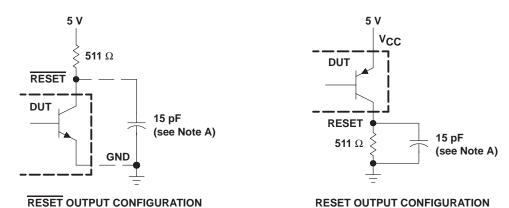
	PARAMETER	TEST COND	TEST CONDITIONS				
			MIN	TYP <sup>†</sup>	MAX		
V <sub>res</sub> ‡	Power-up reset voltage	V <sub>CC</sub> = VSU,	$V_{OL} = 0.4 \text{ V}, I_{OL} = 1 \text{ mA}$		0.8		V
Icc	Supply current	1 <u>VSU</u> = 18 V, 2 <u>VSU</u> = 2 V, 1 <u>RESIN</u> and 2 <u>RESIN</u> at V <sub>CC</sub> , 1 <u>VSO</u> and 2 <u>VSO</u> at 0 V	T <sub>A</sub> = 25°C			5	mA

# switching characteristics, $V_{CC}$ = 5 V, $C_T$ open, $T_A$ = 25°C

	PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
tPLH	Propagation delay time, low-to-high-level output	RESIN	RESET			270	500	ns
<sup>t</sup> PHL	Propagation delay time, high-to-low-level output	RESIN	RESET			270	500	ns
t <sub>r</sub>	Rise time		RESET	See Figures 1			75	20
tf	Fall time		KESET	and 3		150		ns
t <sub>r</sub>	Rise time		DECET			75		no
t <sub>f</sub>	Fall time		RESET				50	ns
+	Minimum effective pulse duration	RESIN		See Figure 2a		150		ns
<sup>t</sup> w(min)	willimum enective pulse duration	VSU		See Figure 2b		100		115

<sup>†</sup> Typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C. ‡ This is the lowest voltage at which RESET becomes active.

## PARAMETER MEASUREMENT INFORMATION



NOTE A: This includes jig and probe capacitance.

Figure 1. RESET and RESET Output Configurations

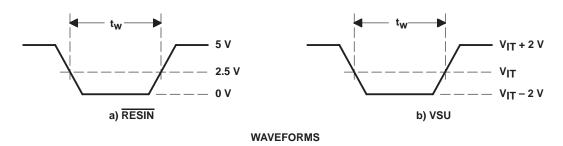


Figure 2. Input Pulse Definition

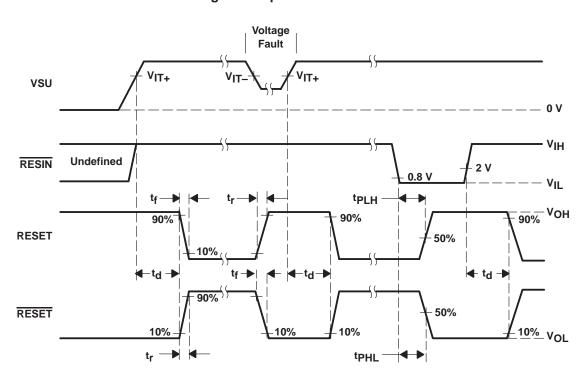
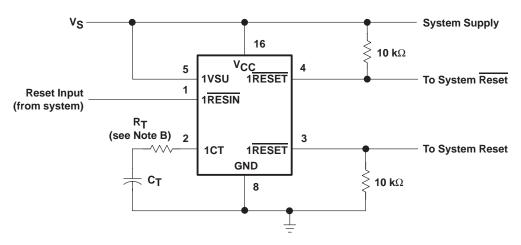


Figure 3. Voltage Waveforms



## **APPLICATION INFORMATION**



NOTE B: When  $V_{CC}$  and 1VSU are connected to the same point, it is recommended that series resistance (R<sub>T</sub>) be added between the time-delay programming capacitor (C<sub>T</sub>) and the voltage-supervisor device terminal (1CT). The suggested R<sub>T</sub> value is given by:

$$R_T > \frac{V_I - V_{IT-}}{1 \times 10^{-3}}$$
, where  $V_I = \left( \text{the lesser of 7.1 V or V}_S \right)$ 

When this series resistor is used, the  $t_{\mbox{\scriptsize d}}$  calculation is as follows:

$$t_{d} = \frac{1.3 - \left[ ((6.5E-5) \times 10^{-5}) \times R_{T} \right]}{6.5 \times 10^{-5}} \times C_{T}$$

Figure 4. System Reset Controller With Undervoltage Sensing

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#### PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
TL7770-12CDWR	ACTIVE	SOIC	DW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	7770-12C	Samples
TL7770-5CDW	ACTIVE	SOIC	DW	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	TL7770-5C	Samples
TL7770-5CDWR	ACTIVE	SOIC	DW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	TL7770-5C	Samples
TL7770-5CN	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	TL7770-5CN	Samples
TL7770-5IDW	ACTIVE	SOIC	DW	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL7770-5I	Samples
TL7770-5IDWG4	ACTIVE	SOIC	DW	16	40	TBD	Call TI	Call TI	-40 to 85		Samples
TL7770-5IDWR	ACTIVE	SOIC	DW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL7770-5I	Samples
TL7770-5IDWRE4	ACTIVE	SOIC	DW	16	2000	TBD	Call TI	Call TI	-40 to 85		Samples

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.



## **PACKAGE OPTION ADDENDUM**

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(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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## **PACKAGE MATERIALS INFORMATION**

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## TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL7770-12CDWR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
TL7770-5CDWR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
TL7770-5IDWR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1

**PACKAGE MATERIALS INFORMATION** 

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## \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TL7770-12CDWR	SOIC	DW	16	2000	350.0	350.0	43.0
TL7770-5CDWR	SOIC	DW	16	2000	350.0	350.0	43.0
TL7770-5IDWR	SOIC	DW	16	2000	350.0	350.0	43.0

# **PACKAGE MATERIALS INFORMATION**

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## **TUBE**



## \*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
TL7770-5CDW	DW	SOIC	16	40	506.98	12.7	4826	6.6
TL7770-5CN	N	PDIP	16	25	506	13.97	11230	4.32
TL7770-5IDW	DW	SOIC	16	40	506.98	12.7	4826	6.6

7.5 x 10.3, 1.27 mm pitch

SMALL OUTLINE INTEGRATED CIRCUIT

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.





SOIC



## NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing
- per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.
- 5. Reference JEDEC registration MS-013.



SOIC



## NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOIC



#### NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



# N (R-PDIP-T\*\*)

## PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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